

Bonder機台簡介

- Equipment---AWB-08
- Separation between platens up to 30 mm
- Automatic PC control & data acquisition
- Application of High Voltage up to 2.5 kV
- Temperatures up to 560 °C
- Forces up to 40,000 N (25 kN - standard machine, 40 kN option)
- Self-contained dry pumping system for vacuum up to 10^{-6} mbar range
- Forced nitrogen cooling

